

REMARKS

By the present Amendment, claims 1, 5 and 6 have been amended to define certain aspects of the invention with greater precision. More specifically, the bismaleimide compounds represented by the formula (1) in claims 1, 5 and 6 have been amended to recite (a) the integer of "m" denotes "2 or more" and (b) the linkage "X" represents "O, SO₂, S, CO or a direct bond". The scope of the currently amended claims is supported by the specification such as Examples 1 to 11 and 14.

The present Amendment clearly makes the present invention distinguishable from references that the Examiner cited in the Office Action. First, as the Examiner explicitly noted in the Action, Yonezawa et al., U.S. Patent No. 4,362,826, shows only specific bismaleimides incorporated into polyamic acid varnishes that, with respect to the previously claimed formulae, provided m=0 or 1 and X=O, CH₂, S, SO₂, C(CH₃)₂, or a direct bond (column 1, line 55 to column 2, line 10). Thus, the presently claimed invention where (b) m=2 or more is clearly not anticipated by Yonezawa et al.

Secondly, Matsuura et al., U.S. Patent No. 5,608,013, discloses a polyimide composition comprising certain types of polymaleimide, which are used as adhesives in metal-clad laminates. However, the disclosed polymaleimides are outside the scope of the present invention. More specifically, in Matsuura et al., there is no disclosed polymaleimide that satisfies both (a) the integer of "m" denotes "2 or more" and (b) the linkage of "X" represents "O, SO₂, S, CO or a direct bond" when they are applied to applicants' formula(1). Accordingly, the stated rejection based on this patent also cannot be maintained.

Finally, Matsuura et al., U.S. Patent No. 5,508,357, also discloses a polyimide composition comprising certain types of polymaleimide to form a thermosetting resin. However, as explained in the previous paragraph, there is no disclosed polymaleimide that satisfies both (a) the integer of "m" denotes "2 or more" and (b) the linkage of "X" represents "O, SO₂, S, CO or a direct bond" when it is applied to applicants' formula(1). Thus, this rejection likewise cannot be maintained against the claims now of record.

For all of the reasons set forth above, applicants respectfully submit that the claims of record overcome all of the rejections set forth in the Action and are patentable over the cited prior art. Accordingly, reconsideration and allowance of the present application are respectfully requested.

Should the Examiner have any questions concerning the subject application, the Examiner is invited to contact the undersigned attorney at the number provided below.

Respectfully submitted,

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